SN54ABT16841...WD PACKAGE

SN74ABT16841 . . . DL PACKAGE

SCBS222C - SEPTEMBER 1992 - REVISED MAY 1997

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 0.8 V at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center **Spacings**

#### description

These 20-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

(TOP VIEW) 56 U 1LE 1OF 55 1D1 1Q1 **1**2 1Q2 43 54 1D2 GND 4 53 | GND 1Q3 **[**]5 52 L 1D3 1Q4 **[**]6 51 1D4 50 | V<sub>CC</sub> V<sub>CC</sub> 47 1Q5 🛮 8 49 🛮 1D5 1Q6 49 48 1 1D6 1Q7 4 10 47 **∐** 1D7 GND 🛚 11 46 | GND 1Q8 L 12 45 1D8 1Q9 13 44 L 1D9 43 🛮 1D10 1Q10 L 14 2Q1 L 15 42 2D1 2Q2 L 16 41 2D2 2Q3 [] 17 40 2D3 GND L 18 39 l gnd 19 38 2D4 2Q4 L

37 D 2D5

36 2D6

35 🛮 V<sub>CC</sub>

34 2D7

32 | GND

31 2D9

30 D 2D10

29 | 2LE

∐ 2D8

33

2Q5 **2**0

2Q8 L

2Q10

2OE

GND 25

2Q9 26

21 2Q6 L

22  $V_{CC}$ 2Q7 🛮 23

24

27

28

The 'ABT16841 can be used as two 10-bit latches or one 20-bit latch. The 20 transparent D-type latches provide true data at the outputs. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the D inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (1<del>OE</del> or 2<del>OE</del>) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

The output-enable input does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.



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SCBS222C - SEPTEMBER 1992 - REVISED MAY 1997

### description (continued)

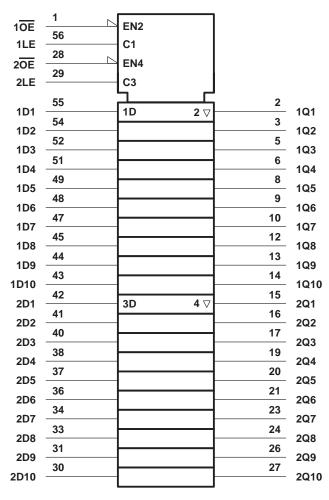
When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16841 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16841 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each 10-bit latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q <sub>0</sub>
Н	Χ	Χ	Z

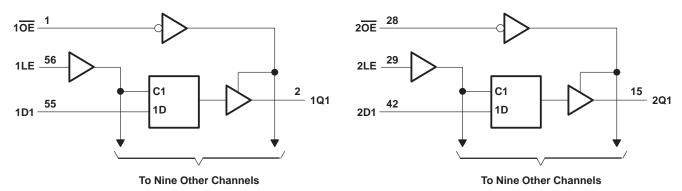
### logic symbol†



 $<sup>^\</sup>dagger$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16841	96 mA
SN74ABT16841	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	−50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DL package	74°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

### recommended operating conditions (see Note 3)

			SN54AB	Г16841	SN74AB1	Γ16841	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V	
V <sub>IL</sub>	V <sub>IL</sub> Low-level input voltage					0.8	V
VI	Input voltage	0	VCC	0	VCC	V	
IOH	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SCBS222C - SEPTEMBER 1992 - REVISED MAY 1997

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ARAMETER	TEST C	ONDITIONS	Т	A = 25°C	;	SN54AB	T16841	SN74AB1	16841	UNIT
	ARAMETER	TEST CO	DINDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT
٧ıK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/~		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
V/01		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
V <sub>hys</sub>					100						mV
1.		$V_{CC} = 0 \text{ to } 5.5 \text{ V}$	$V_1 = V_{CC}$ or GND			±1				±1	μА
l <sub>l</sub>		$V_{CC} = 5 \text{ V}, \text{ V}_{I} = 1$					±5			μΑ	
lozpu	j‡	$V_{CC} = 0 \text{ to } 2.1 \text{ V}$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}$			±50		±50		±50	μА	
IOZPE	<sub>5</sub> ‡	V <sub>CC</sub> = 2.1 V to 0 V <sub>O</sub> = 0.5 V to 2.7			±50		±50		±50	μА	
lozh		$V_{CC} = 2.1 \text{ V} \text{ to } 5$ $V_{O} = 2.7 \text{ V}, \overline{\text{OE}} 2$				10		10		10	μА
lozL		$V_{CC} = 2.1 \text{ V to } 5$ $V_{O} = 0.5 \text{ V}, \overline{\text{OE}} 2$				-10		-10		-10	μА
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 5.5 V			50		50		50	μΑ
IO§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
	Outputs high	.,	•			0.5		0.5			
ICC	Outputs low	$V_{CC} = 5.5 \text{ V, I}_{O}$ $V_{I} = V_{CC} \text{ or GNI}$				89		89		89	mA
	Outputs disabled	A A - ACC OL GIAD				0.5		0.5		0.5	
ΔICC¶	$\Delta I_{CC}$ V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND					1.5		1.5		1.5	mA
C <sub>i</sub>	$V_{l} = 2.5 \text{ V or } 0.5 \text{ V}$				3.5						pF
Co		$V_0 = 2.5 \text{ V or } 0.5$	5 V		7.5						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54AE		
			MIN MAX	UNIT
		MIN MAX		
t <sub>W</sub>	Pulse duration, LE high or low	4	4	ns
t <sub>su</sub>	Setup time, data before LE↓	3	3	ns
th	Hold time, data after LE↓	2.6	2.6	ns



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> This parameter is characterized, but not production tested.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

SCBS222C - SEPTEMBER 1992 - REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		9				
		V <sub>CC</sub> = T <sub>A</sub> = 2	5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX	1		
t <sub>W</sub>	Pulse duration, LE high or low	4		4		ns
t <sub>su</sub>	Setup time, data before LE↓	1		1		ns
th	Hold time, data after LE↓	2		2		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

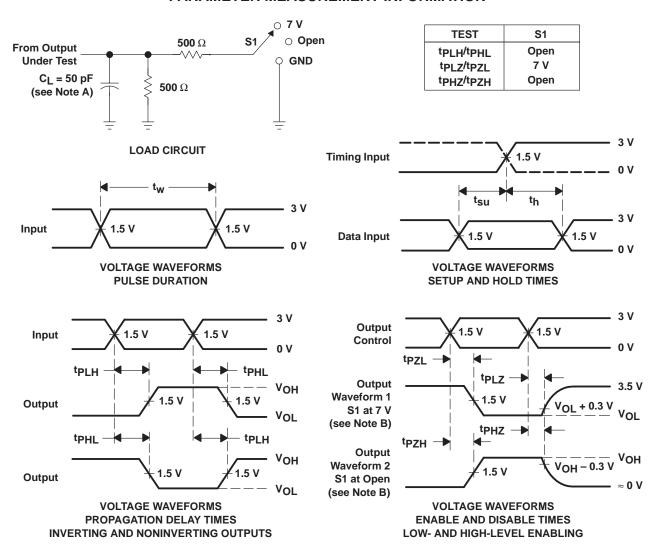
				SN5	4ABT16	841		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V A = 25°C	<i>'</i> ,	MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	D	Q	1.1	3.2	4.3	1.1	5.7	ns
t <sub>PHL</sub>	Б	ά	1.6	3.5	4.5	1.6	5.3	113
t <sub>PLH</sub>	LE	Q	1.1	3.2	4.4	1.1	5.6	ns
<sup>t</sup> PHL	LL	ά	1.6	3.4	5	1.6	5.5	113
<sup>t</sup> PZH	ŌĒ	Q	1.2	3.2	4.7	1.2	5.8	ns
tPZL	OE	ά	1.7	3.6	5	1.7	5.7	115
<sup>t</sup> PHZ	ŌĒ	Q	2.2	4.1	6.6	2.2	7.7	ns
<sup>t</sup> PLZ	OE .	ď	1.9	4.4	5.8	1.2	8.4	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT16	841		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	D	Q	1.1	3.2	4.3	1.1	5	ns
t <sub>PHL</sub>	U	ď	1.6	3.5	4.5	1.6	5.1	115
t <sub>PLH</sub>	LE	Q	1.1	3.2	4.4	1.1	5	ns
t <sub>PHL</sub>	LL	Q	1.6	3.4	4.6	1.6	5	115
<sup>t</sup> PZH	ŌĒ	Q	1.2	3.2	4.7	1.2	5.7	ns
t <sub>PZL</sub>	OE .	Q	1.7	3.6	5	1.7	5.6	115
<sup>t</sup> PHZ	ŌĒ	Q	2.2	4.1	5.7	2.2	6.5	ne
tPLZ	) OE		1.9	4.4	5.8	1.9	7.1	ns

SCBS222C - SEPTEMBER 1992 - REVISED MAY 1997

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{Q}$  = 50  $\Omega$ ,  $t_{f}$   $\leq$  2.5 ns,  $t_{f}$   $\leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 11-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74ABT16841DL	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16841
SN74ABT16841DL.B	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16841
SN74ABT16841DLR	Active	Production	SSOP (DL)   56	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16841
SN74ABT16841DLR.B	Active	Production	SSOP (DL)   56	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16841

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

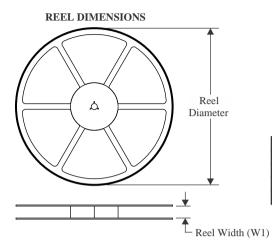
<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

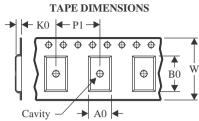
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width						
В0	Dimension designed to accommodate the component length						
K0	Dimension designed to accommodate the component thickness						
W	Overall width of the carrier tape						
P1	Pitch between successive cavity centers						

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16841DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025



### \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74ABT16841DLR	SSOP	DL	56	1000	356.0	356.0	53.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**

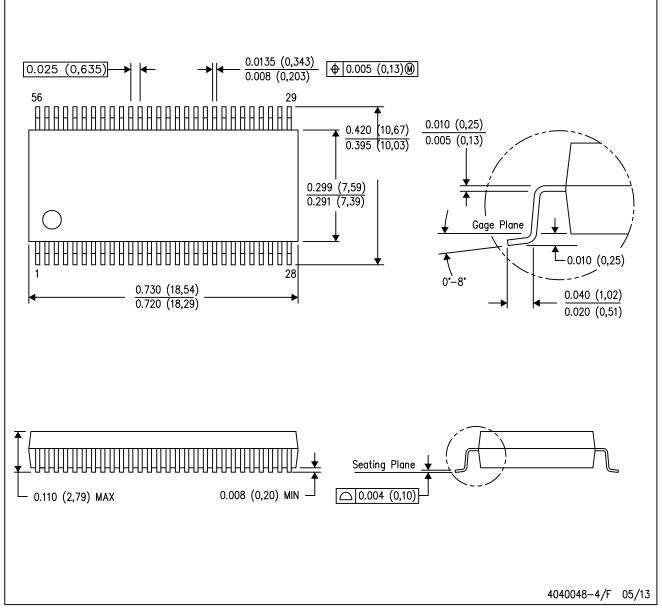


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT16841DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ABT16841DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

# DL (R-PDSO-G56)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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